

IR-2550 DIV (2-3619)

TITLE: **CHIP SCALE SURFACE MOUNTED DEVICE AND**
PROCESS OF MANUFACTURE

ABSTRACT OF THE DISCLOSURE

5 A chip scale package has a semiconductor MOSFET die which has a
top electrode surface covered with a layer of a photosensitive liquid epoxy which is
photolithographically patterned to expose portions of the electrode surface and to act
as a passivation layer and as a solder mask. A solderable contact layer is then formed
over the passivation layer. The individual die are mounted drain side down in a
metal clip or can with the drain electrode disposed coplanar with a flange extending
from the can bottom.